#### **Features**

- Fast Read Access Time 150 ns
- Fast Byte Write 200 µs or 1 ms
- Self-Timed Byte Write Cycle
  - Internal Address and Data Latches
  - Internal Control Timer
  - Automatic Clear Before Write
- Direct Microprocessor Control
  - DATA POLLING
  - READY/BUSY Open Drain Output
- Low Power
  - 30 mA Active Current
  - 100 µa CMOS Standby Current
- · High Reliability
  - Endurance: 10<sup>4</sup> or 10<sup>5</sup> Cycles
  - Data Retention: 10 Years
- 5V ± 10% Supply
- CMOS & TTL Compatible Inputs and Outputs
- JEDEC Approved Byte Wide Pinout
- Commercial and Industrial Temperature Ranges

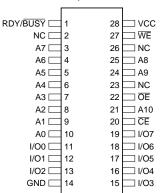
#### **Description**

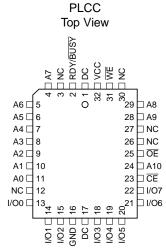
The AT28C17 is a low-power, high-performance Electrically Erasable and Program-mable Read Only Memory with easy to use features. The AT28C17 is a 16K memory organized as 2,048 words by 8 bits. The device is manufactured with Atmel's reliable nonvolatile CMOS technology. *(continued)* 

### **Pin Configurations**

Pin Name	Function
A0 - A10	Addresses
CE	Chip Enable
ŌĒ	Output Enable
WE	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
RDY/BUSY	Ready/Busy Output
NC	No Connect
DC	Don't Connect







PLCC package pins 1 and 17 are DON'T CONNECT.



Note:



16K (2K x 8) Parallel EEPROMs

AT28C17

Rev. 0541B-10/98

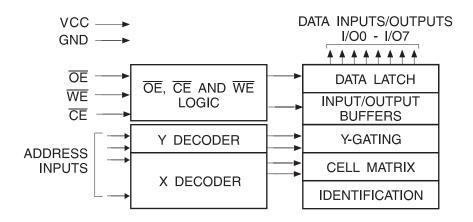


The AT28C17 is accessed like a static RAM for the read or write cycles without the need of external components. During a byte write, the address and data are latched internally, freeing the microprocessor address and data bus for other operations. Following the initiation of a write cycle, the device will go to a busy state and automatically clear and write the latched data using an internal control timer. The device includes two methods for detecting the end of a write cycle, level detection of RDY/BUSY and DATA POLLING of I/O<sub>7</sub>. Once the end of a write cycle has been detected, a new access for a read or a write can begin.

The CMOS technology offers fast access times of 150 ns at low power dissipation. When the chip is deselected the standby current is less than 100  $\mu$ A.

Atmel's 28C17 has additional features to ensure high quality and manufacturability. The device utilizes error correction internally for extended endurance and for improved data retention characteristics. An extra 32 bytes of EEPROM are available for device identification or tracking.

#### **Block Diagram**



### Absolute Maximum Ratings\*

Temperature Under Bias55°C to +125°C
Storage Temperature65°C to +150°C
All Input Voltages (including NC Pins) with Respect to Ground0.6V to +6.25V
All Output Voltages with Respect to Ground0.6V to V <sub>CC</sub> + 0.6V
Voltage on $\overline{\text{OE}}$ and A9 with Respect to Ground0.6V to +13.5V

\*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability

#### **Device Operation**

**READ:** The AT28C17 is accessed like a Static RAM. When  $\overline{\text{CE}}$  and  $\overline{\text{OE}}$  are low and  $\overline{\text{WE}}$  is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in a high impedance state whenever  $\overline{\text{CE}}$  or  $\overline{\text{OE}}$  is high. This dual line control gives designers increased flexibility in preventing bus contention.

BYTE WRITE: Writing data into the AT28C17 is similar to writing into a Static RAM. A low pulse on the  $\overline{WE}$  or  $\overline{CE}$  input with  $\overline{OE}$  high and  $\overline{CE}$  or  $\overline{WE}$  low (respectively) initiates a byte write. The address location is latched on the last falling edge of  $\overline{WE}$  (or  $\overline{CE}$ ); the new data is latched on the first rising edge. Internally, the device performs a self-clear before write. Once a byte write has been started, it will automatically time itself to completion. Once a programming operation has been initiated and for the duration of  $t_{WC}$ , a read operation will effectively be a polling operation.

**FAST BYTE WRITE:** The AT28C17E offers a byte write time of 200  $\mu$ s maximum. This feature allows the entire device to be rewritten in 0.4 seconds.

**READY/BUSY**: Pin 1 is an open drain READY/BUSY output that can be used to detect the end of a write cycle. RDY/BUSY is actively pulled low during the write cycle and is released at the completion of the write. The open drain

connection allows for OR-tying of several devices to the same RDY/BUSY line.

 $\overline{\text{DATA}}$  **POLLING:** The AT28C17 provides  $\overline{\text{DATA}}$  POLLING to signal the completion of a write cycle. During a write cycle, an attempted read of the data being written results in the complement of that data for I/O<sub>7</sub> (the other outputs are indeterminate). When the write cycle is finished, true data appears on all outputs.

**WRITE PROTECTION:** Inadvertent writes to the device are protected against in the following ways: (a)  $V_{CC}$  sense—if  $V_{CC}$  is below 3.8V (typical) the write function is inhibited; (b)  $V_{CC}$  power on delay once  $V_{CC}$  has reached 3.8V the device will automatically time out 5 ms (typical) before allowing a byte write; and (c) write inhibit—holding any one of  $\overline{OE}$  low,  $\overline{CE}$  high or  $\overline{WE}$  high inhibits byte write cycles.

**CHIP CLEAR:** The contents of the entire memory of the AT28C17 may be set to the high state by the CHIP CLEAR operation. By setting  $\overline{CE}$  low and  $\overline{OE}$  to 12 volts, the chip is cleared when a 10 msec low pulse is applied to  $\overline{WE}$ .

**DEVICE IDENTIFICATION:** An extra 32 bytes of EEPROM memory are available to the user for device identification. By raising A9 to  $12\pm0.5V$  and using address locations 7E0H to 7FFH the additional bytes may be written to or read from in the same manner as the regular memory array.





## **DC and AC Operating Range**

		AT28C17-15
Operating	Com.	0°C - 70°C
Operating Temperature (Case)	Ind.	-40°C - 85°C
V <sub>CC</sub> Power Supply		5V ± 10%

## **Operating Modes**

Mode	CE	ŌĒ	WE	I/O
Read	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>IH</sub>	D <sub>OUT</sub>
Write <sup>(2)</sup>	V <sub>IL</sub>	V <sub>IH</sub>	V <sub>IL</sub>	D <sub>IN</sub>
Standby/Write Inhibit	V <sub>IH</sub>	X <sup>(1)</sup>	X	High Z
Write Inhibit	X	X	V <sub>IH</sub>	
Write Inhibit	X	V <sub>IL</sub>	Х	
Output Disable	Х	V <sub>IH</sub>	Х	High Z
Chip Erase	V <sub>IL</sub>	V <sub>H</sub> <sup>(3)</sup>	V <sub>IL</sub>	High Z

Notes: 1. X can be V<sub>IL</sub> or V<sub>IH</sub>.

2. Refer to AC Programming Waveforms.

3.  $V_H = 12.0V \pm 0.5V$ .

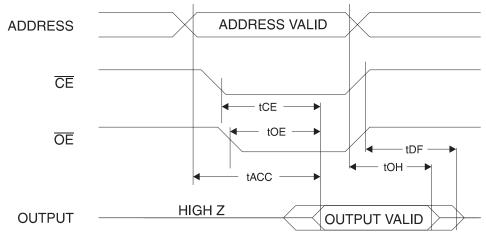
### **DC Characteristics**

Symbol	Parameter	Condition		Min	Max	Units
ILI	Input Load Current	$V_{IN} = 0V \text{ to } V_{CC} + 1V$			10	μΑ
I <sub>LO</sub>	Output Leakage Current	$V_{I/O} = 0V \text{ to } V_{CC}$			10	μΑ
I <sub>SB1</sub>	V <sub>CC</sub> Standby Current CMOS	$\overline{\text{CE}} = \text{V}_{\text{CC}} - 0.3 \text{V to V}_{\text{CC}} + 1.0$	ΟV		100	μΑ
	V Chan dlay Cymra at TTI	<u>CF</u> 2.0\/+2\/4.0\/	Com.		2	mA
V <sub>CC</sub> Standby Curre	V <sub>CC</sub> Standby Current TTL	$\overline{\text{CE}} = 2.0 \text{V to V}_{\text{CC}} + 1.0 \text{V}$	Ind.		3	mA
	V <sub>CC</sub> Active Current AC	f = 5 MHz; I <sub>OUT</sub> = 0 mA	Com.		30	mA
Icc		CE = V <sub>IL</sub>	Ind.		45	mA
V <sub>IL</sub>	Input Low Voltage				0.8	V
V <sub>IH</sub>	Input High Voltage			2.0		V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2.1 mA = 4.0 for RDY/BUSY			.4	V
V <sub>OH</sub>	Output High Voltage	Ι <sub>ΟΗ</sub> = -400 μΑ		2.4		V

#### **AC Read Characteristics**

		AT28C17-15		
Symbol	Parameter	Min	Max	Units
t <sub>ACC</sub>	Address to Output Delay		150	ns
t <sub>CE</sub> <sup>(1)</sup>	CE to Output Delay		150	ns
t <sub>OE</sub> <sup>(2)</sup>	OE to Output Delay	10	70	ns
t <sub>DF</sub> <sup>(3)(4)</sup>	CE or OE High to Output Float	0	50	ns
t <sub>OH</sub>	Output Hold from OE, CE or Address, whichever occurred first	0		ns

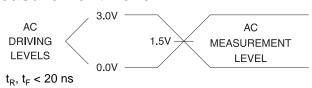
### AC Read Waveforms<sup>(1)(2)(3)(4)</sup>



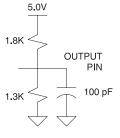
Notes: 1.  $\overline{\text{CE}}$  may be delayed up to  $t_{\text{ACC}}$  -  $t_{\text{CE}}$  after the address transition without impact on  $t_{\text{ACC}}$ .

- 2.  $\overline{\text{OE}}$  may be delayed up to  $t_{\text{CE}}$   $t_{\text{OE}}$  after the falling edge of  $\overline{\text{CE}}$  without impact on  $t_{\text{CE}}$  or by  $t_{\text{ACC}}$   $t_{\text{OE}}$  after an address change without impact on  $t_{\text{ACC}}$ .
- 3.  $t_{DF}$  is specified from  $\overline{OE}$  or  $\overline{CE}$  whichever occurs first ( $C_L = 5 \text{ pF}$ ).
- 4. This parameter is characterized and is not 100% tested.

# Input Test Waveforms and Measurement Level



## **Output Test Load**



## Pin Capacitance

 $f = 1 \text{ MHz}, T = 25^{\circ}C^{(1)}$ 

Symbol	Тур	Max	Units	Conditions
C <sub>IN</sub>	4	6	pF	$V_{IN} = 0V$
C <sub>OUT</sub>	8	12	pF	V <sub>OUT</sub> = 0V

Note: 1. This parameter is characterized and is not 100% tested.



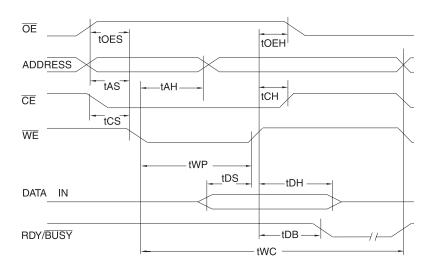


### **AC Write Characteristics**

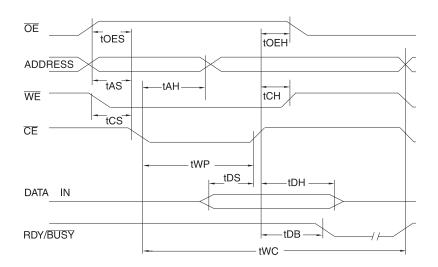
Symbol	Parameter	Min	Тур	Max	Units	
t <sub>AS</sub> , t <sub>OES</sub>	Address, OE Set-up Time		10			ns
t <sub>AH</sub>	Address Hold Time		50			ns
t <sub>WP</sub>	Write Pulse Width (WE or CE)		100		1000	ns
t <sub>DS</sub>	Data Set-up Time	50			ns	
t <sub>DH</sub> , t <sub>OEH</sub>	Data, <del>OE</del> Hold Time		10			ns
t <sub>CS</sub> , t <sub>CH</sub>	CE to WE and WE to CE Set-up and Hold Time		0			ns
t <sub>DB</sub>	Time to Device Busy				50	ns
	Maile Coole Time	AT28C17		0.5	1.0	ms
t <sub>WC</sub>	Write Cycle Time	AT28C17E		100	200	μs

### **AC Write Waveforms**

#### **WE** Controlled



### **CE** Controlled



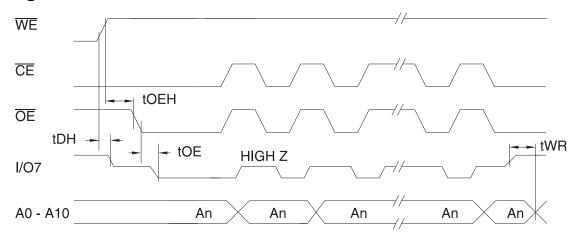
## **Data** Polling Characteristics<sup>(1)</sup>

Symbol	Parameter	Min	Тур	Max	Units
t <sub>DH</sub>	Data Hold Time	10			ns
t <sub>OEH</sub>	OE Hold Time	10			ns
t <sub>OE</sub>	OE to Output Delay <sup>(2)</sup>				ns
t <sub>WR</sub>	Write Recovery Time	0			ns

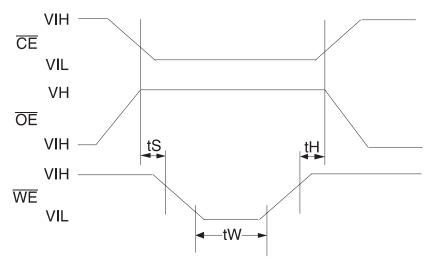
Notes: 1. These parameters are characterized and not 100% tested.

2. See AC Read Characteristics.

## **Data** Polling Waveforms



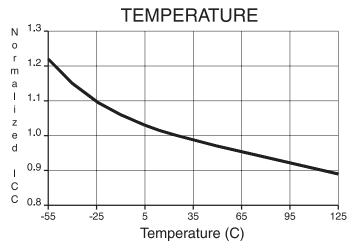
### **Chip Erase Waveforms**



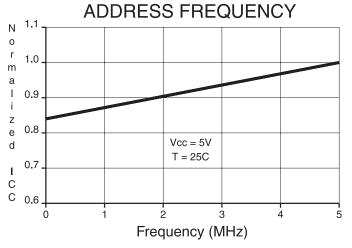
$$\begin{split} t_S &= t_H = 1 \; \mu sec \; (min.) \\ t_W &= 10 \; msec \; (min.) \\ V_H &= 12.0 \pm 0.5 V \end{split}$$



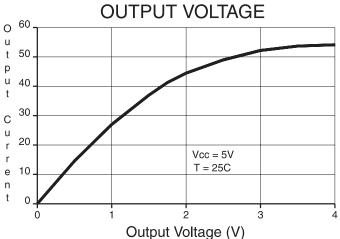
#### NORMALIZED SUPPLY CURRENT vs.



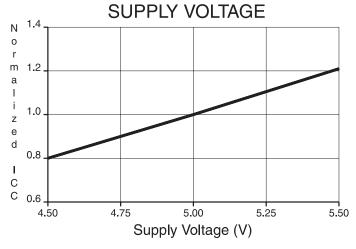
## NORMALIZED SUPPLY CURRENT vs.



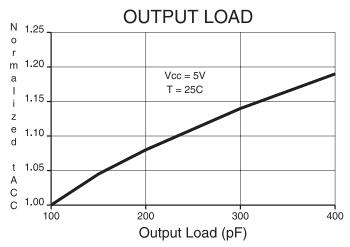
## OUTPUT SINK CURRENT vs.



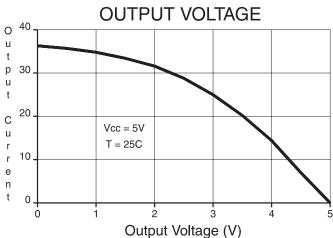
### NORMALIZED SUPPLY CURRENT vs.



### NORMALIZED ACCESS TIME vs.



## OUTPUT SOURCE CURRENT vs.



## **Ordering Information**<sup>(1)</sup>

t <sub>ACC</sub>	I <sub>CC</sub> (mA)				
(ns)	Active	Standby	Ordering Code	Package	Operation Range
150	30	0.1	AT28C17(E)-15JC	32J	Commercial
			AT28C17(E)-15PC	28P6	(0°C to 70°C)
			AT28C17(E)-15SC	28S	
	45	0.1	AT28C17(E)-15JI	32J	Industrial
			AT28C17(E)-15PI	28P6	(-40°C to 85°C)
			AT28C17(E)-15SI	28S	

- Notes: 1. See Valid Part Numbers table below.
  - 2. The 28C17 200 ns and 250 ns speed selections have been removed from valid selections table and are replaced by the faster 150 ns  $T_{AA}$  offering.
  - 3. The 28C17 ceramic and LCC package offerings have been removed. New designs should utilize the 28C256 ceramic offerings.

#### **Valid Part Numbers**

The following table lists standard Atmel products that can be ordered.

Device Numbers	Speed	Package and Temperature Combinations	
AT28C17	15	JC, JI, PC, PI, SC, SI	
AT28C17E	15	JC, JI, PC, PI, SC, SI	
AT28C17	-	W	

#### **Die Products**

Reference Section: Parallel EEPROM Die Products

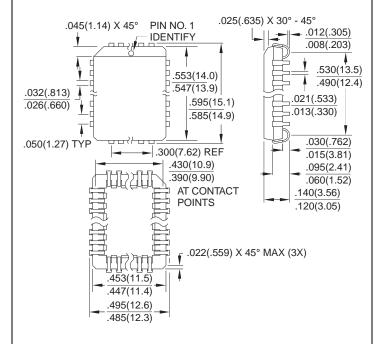
	Package Type			
32J	32-Lead, Plastic J-Leaded Chip Carrier (PLCC)			
28P6	28P6 28-Lead, 0.600" Wide, Plastic Dull Inline Package (PDIP)			
28S	28S 28-Lead, 0.300" Wide, Plastic Gull Wing, Small Outline (SOIC)			
W	Die			
	Options			
Blank	Blank Standard Device: Endurance = 10K Write Cycles; Write Time = 1 ms			
Е	E High Endurance Option: Endurance = 100K Write Cycles; Write Time = 200 μs			





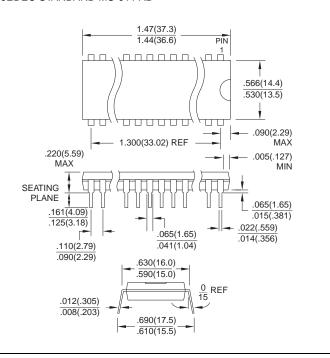
### **Packaging Information**

32J, 32-Lead, Plastic J-Leaded Chip Carrier (PLCC) Dimensions in Inches and (Millimeters) JEDEC STANDARD MS-018 AA



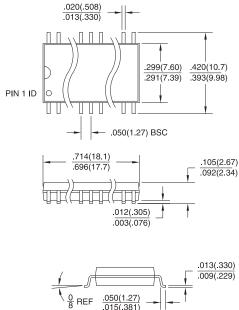
28P6, 28-Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)

Dimensions in Inches and (Millimeters) JEDEC STANDARD MS-011 AB



28S, 24-Lead, 0.300" Wide, Plastic Gull Wing Small Outline (SOIC)

Dimensions in Inches and (Millimeters)







#### **Atmel Headquarters**

Corporate Headquarters

2325 Orchard Parkway San Jose, CA 95131 TEL (408) 441-0311 FAX (408) 487-2600

#### **Europe**

Atmel U.K., Ltd.
Coliseum Business Centre
Riverside Way
Camberley, Surrey GU15 3YL
England
TEL (44) 1276-686677
FAX (44) 1276-686697

#### Asia

Atmel Asia, Ltd. Room 1219 Chinachem Golden Plaza 77 Mody Road Tsimshatsui East Kowloon, Hong Kong TEL (852) 27219778 FAX (852) 27221369

#### Japan

Atmel Japan K.K. Tonetsu Shinkawa Bldg., 9F 1-24-8 Shinkawa Chuo-ku, Tokyo 104-0033 Japan TEL (81) 3-3523-3551 FAX (81) 3-3523-7581

#### **Atmel Operations**

Atmel Colorado Springs

1150 E. Cheyenne Mtn. Blvd. Colorado Springs, CO 80906 TEL (719) 576-3300 FAX (719) 540-1759

#### Atmel Rousset

Zone Industrielle 13106 Rousset Cedex, France TEL (33) 4 42 53 60 00 FAX (33) 4 42 53 60 01

> Fax-on-Demand North America: 1-(800) 292-8635 International: 1-(408) 441-0732

*e-mail* literature@atmel.com

Web Site http://www.atmel.com

*BBS* 1-(408) 436-4309

#### © Atmel Corporation 1998.

Atmel Corporation makes no warranty for the use of its products, other than those expressly contained in the Company's standard warranty which is detailed in Atmel's Terms and Conditions located on the Company's website. The Company assumes no responsibility for any errors which may appear in this document, reserves the right to change devices or specifications detailed herein at any time without notice, and does not make any commitment to update the information contained herein. No licenses to patents or other intellectual property of Atmel are granted by the Company in connection with the sale of Atmel products, expressly or by implication. Atmel's products are not authorized for use as critical components in life support devices or systems.

Marks bearing ® and/or ™ are registered trademarks and trademarks of Atmel Corporation.

Printed on recycled paper.

## **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

### Atmel:

AT28C17E-15PI AT28C17-15JC AT28C17-15PC